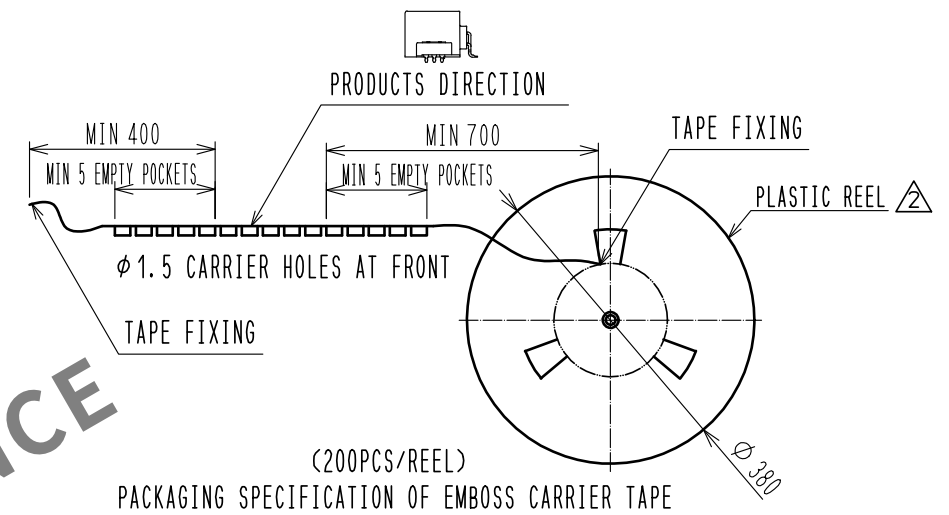
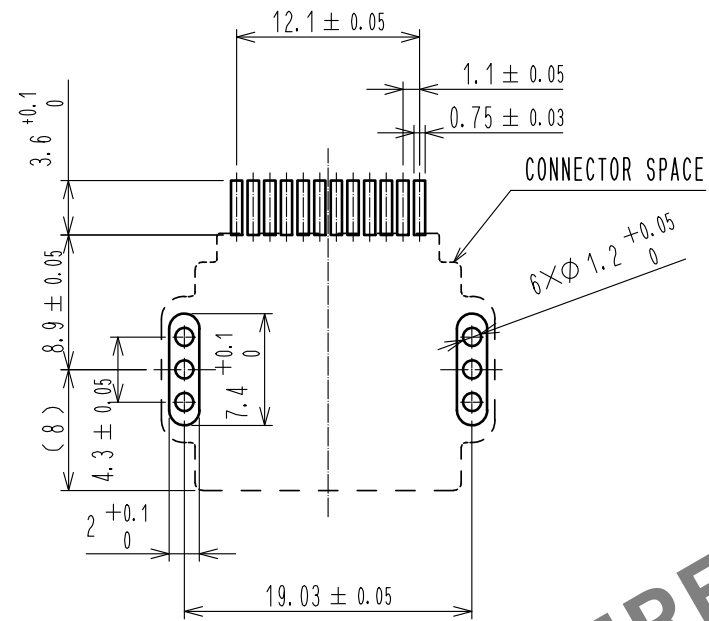
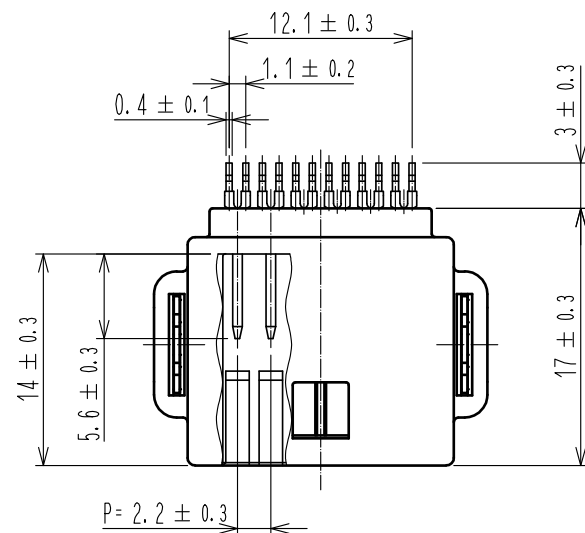
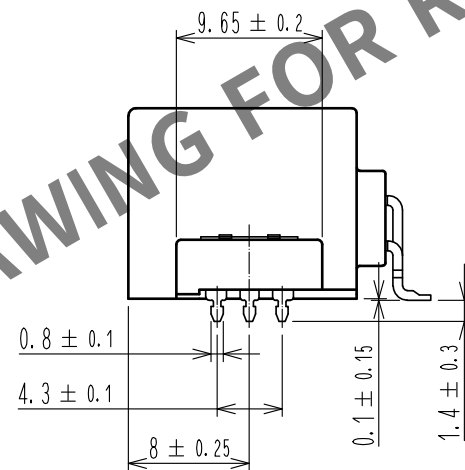
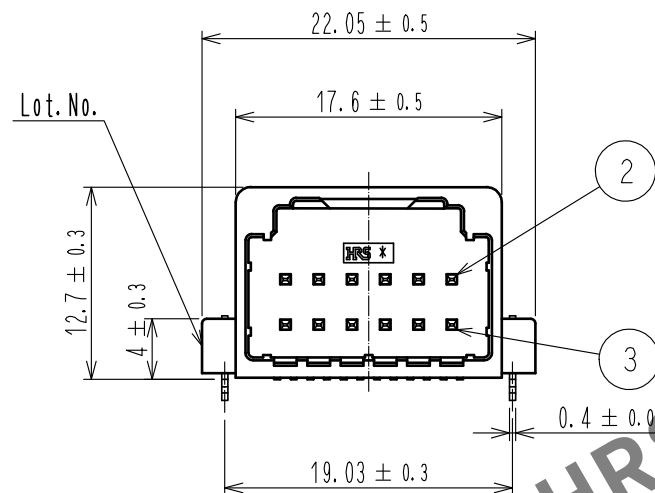


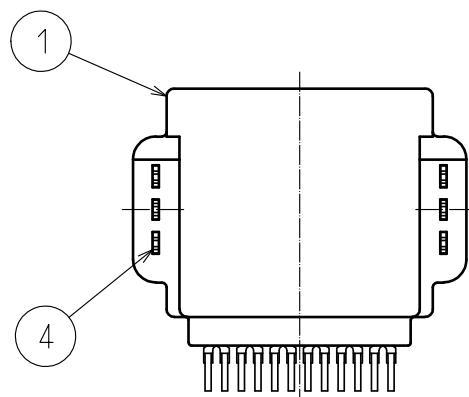
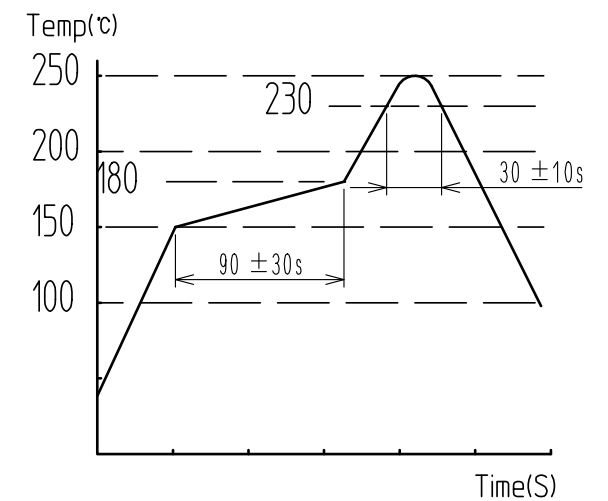
ELV, RoHS COMPLIANT



RECOMMENDED PCB PATTERN



- NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)
REFLOW HEATING METHOD
: IR IN THE AIR OR NITROGEN
NO. OF CYCLES : 2 MAX
PEAK : 250°C
OVER 230°C : 20~40s
PREHEAT : 150~180°C
60~120s
2. TEMPERATURE FOR SOLDERING IRON
: 280~300°C MAX WITHIN 2s
3. CO-PLANARITY SHALL BE 0.1mm MAX.
4. PC BOARD THICKNESS = 1.6mm
5. RECOMMENDED SOLDER THICKNESS = 0.15mm



2	BRASS	TIN PLATED T=0.64	4	BRASS	TIN PLATED T=0.4
1	PPS	LIGHT GRAY	3	BRASS	TIN PLATED T=0.64
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1	COUNT 1	DESCRIPTION OF REVISIONS DIS-T-00006398	DESIGNED DONGCHAN KIM
		APPROVED : KS. SATOH	20070305	DRAWING NO.	EDC-166407-00-00
		CHECKED : AR. SHIRAI	20070301	PART NO.	GT25-12DP-2.2H
		DESIGNED : TY. SAKASHITA	20070301	CODE NO.	CL775-0005-4-00
		DRAWN : TY. SAKASHITA	20070301		